



深圳市佑驰电子有限公司

Specification for Approval

产品名称: 一体系列电感
规格型号: HHMC-0430-3R3-M
产品编号:
日 期: 2020-03-16

1、本承诺书的内容更改需经过双方确认，任一方单独的修改均视为无效。

2、本承诺书在送达客户后，请给予承认并即签回，如无签回下订单的，我司有权以此承认书标准生产，并表示购买方默认许可。

	审核	制作

批准	审核	检验



REVISION					
REV	DESCRIPTION	DATE	DESIGNED	CHECKED	APPROVED
A0	文件建立	2020/03/16	吕秀秀	Bowen	Darren

High Current, Power Inductors

HHMC-0430-3R3-M Power Choke



Description

- Halogen Free
- 125°C maximum total temperature operation
- 4.3x4.3x 3.0mm maximum surface mount package
- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Smart phone POL modules
- SSD modules
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental Data

- Storage temperature range: -55°C to +125 °C
- Operating temperature range: -55°C to +125°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 compliant

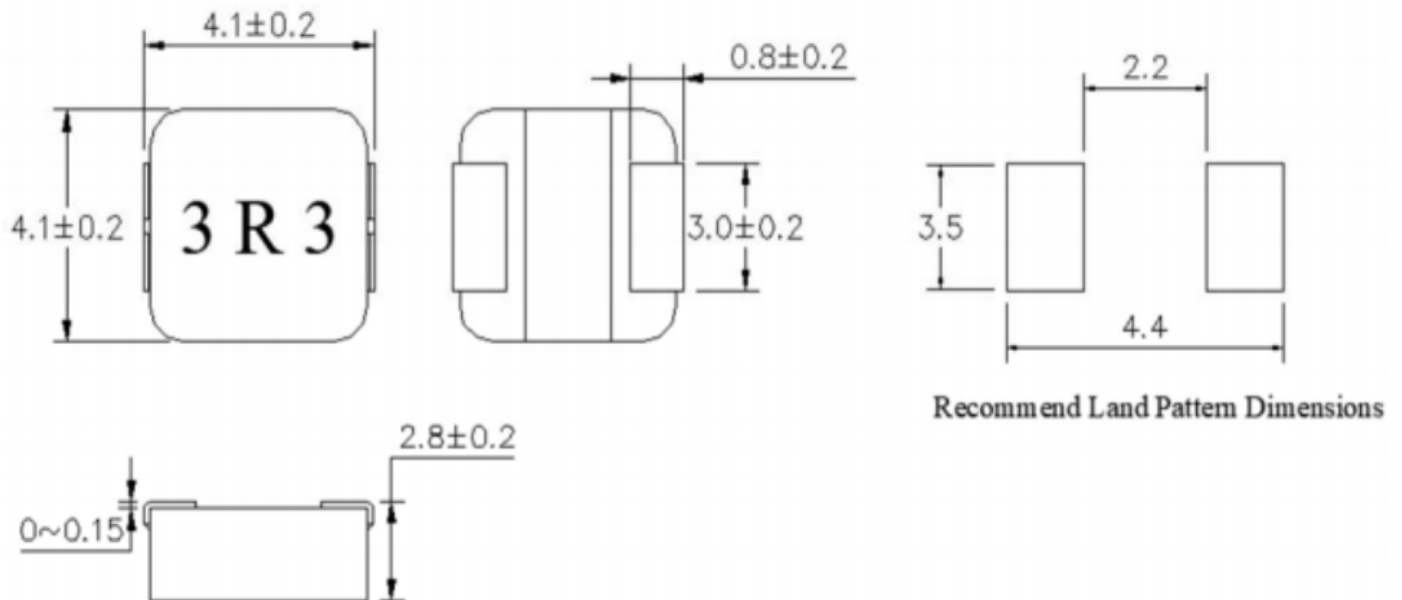
Description												
HHMC-0430-3R3-M				3.3μH				±20 %				
Model				Inductance Value				Inductance Tolerance				
Global Part Number												
H	H	M	C	0	4	3	0	3	R	3	M	
Product Series				Dimensions				Inductance Value				Tolerance

Part No.	Inductance	DC Resistance		Heating Rating Current	Saturation Current
	L0 (μH)	DCR (mΩ)		Idc (A)	Isat (A)
	±20 %, 100 kHz, 1V	TYP.	MAX.	TYP.	TYP.
HHMC-0430-3R3-M	3.3	24.0	28.0	6.6	4.7

Notes

1. All test data is referenced to 25 °C ambient
2. Operating temperature range - 55 °C to + 125 °C
3. Idc(A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)
4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

•Dimensions-mm

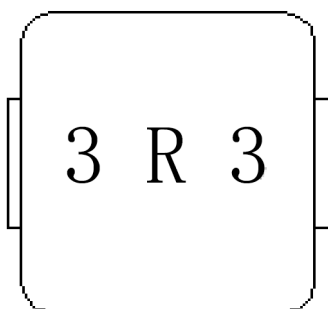


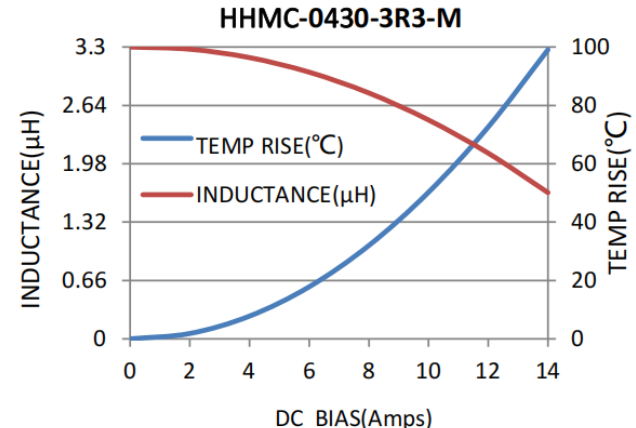
•Marking

The inductor is marked with a 3-digit code

Example - -3.3→3R3

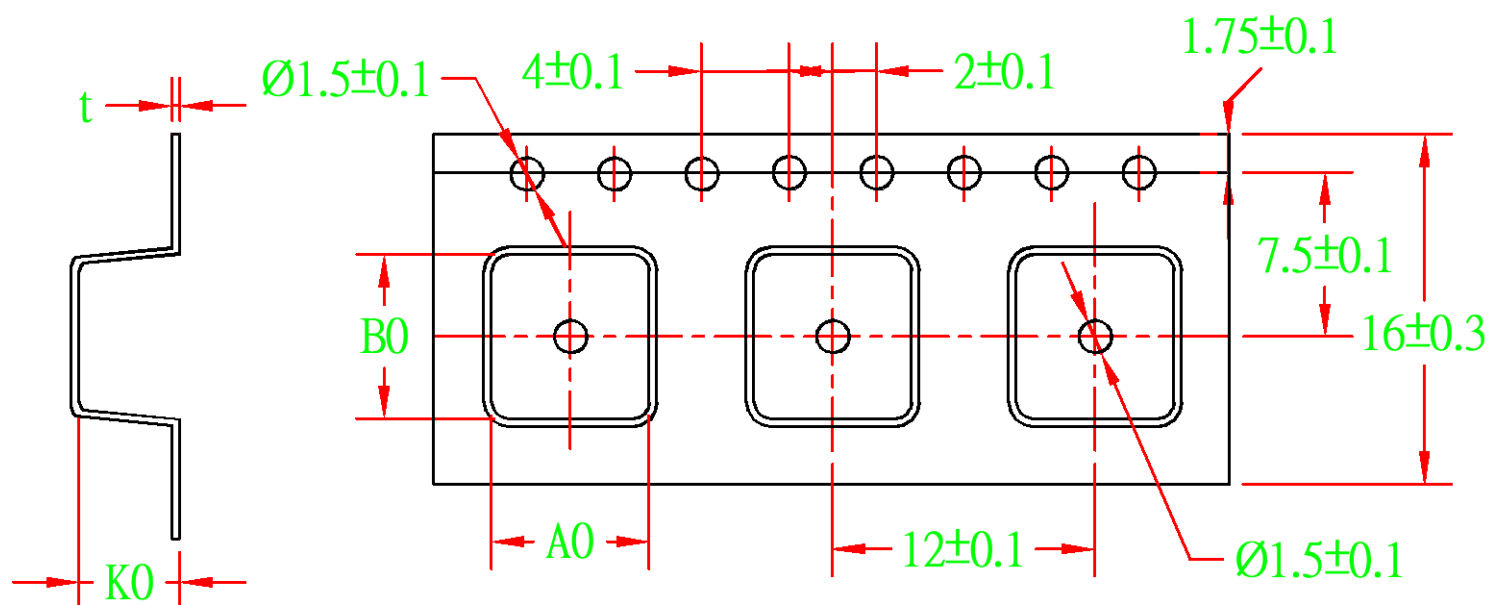
Note : Using Ink for marking



Performance Graphs																												
Test Instruments	Test Condition																											
Wayne kerr 3260B/G LCR Meter Wayne kerr 3265B Bias Current Source	Temperature: 26 ± 3℃ Humidity: < 70% RH Frequency: 100 KHz, 1.0V																											
HHMC-0430-3R3-M <table><caption>Approximate data points from the graph</caption><thead><tr><th>DC BIAS (Amps)</th><th>Temp Rise (°C)</th><th>Inductance (μH)</th></tr></thead><tbody><tr><td>0</td><td>0</td><td>3.3</td></tr><tr><td>2</td><td>2</td><td>3.2</td></tr><tr><td>4</td><td>5</td><td>3.1</td></tr><tr><td>6</td><td>10</td><td>3.0</td></tr><tr><td>8</td><td>18</td><td>2.8</td></tr><tr><td>10</td><td>28</td><td>2.6</td></tr><tr><td>12</td><td>40</td><td>2.3</td></tr><tr><td>14</td><td>55</td><td>2.0</td></tr></tbody></table>	DC BIAS (Amps)	Temp Rise (°C)	Inductance (μH)	0	0	3.3	2	2	3.2	4	5	3.1	6	10	3.0	8	18	2.8	10	28	2.6	12	40	2.3	14	55	2.0	
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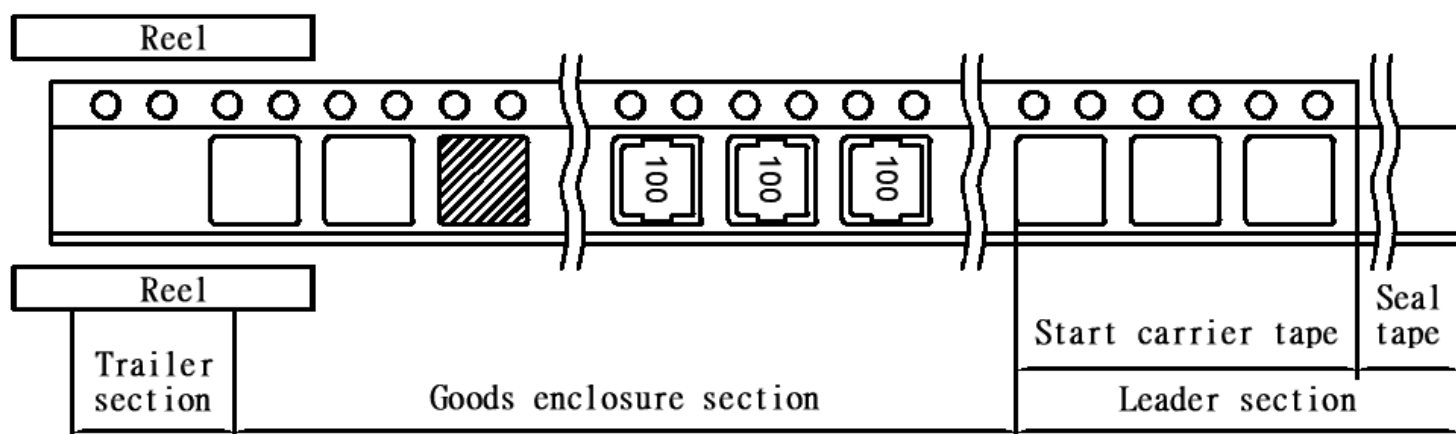
Mechanical Reliability			
No.	Item	Specification and Requirement	Test Method
1	Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	Retention time: 245 ± 5 °C for 5+0/-0.5seconds;
2	Resistance to Soldering Heat	Change from an initial value Inductance:within $\pm 10\%$	Retention time: within 30 seconds 255 ± 5 °C , Three Times;
3	Terminal Strength	No electrode detachment	No electrode detachment should be found when the device is pushed is two directions of X and Y with the force of 17.7N for 60 seconds after soldering between copper plate and the electrodes;
4	Vibration	Inductance change: Within $\pm 10\%$ Without mechanical damage such as break	1. Vibration frequency: (10 Hz to 2000 Hz to 10Hz) in 20 minutes as a period; 2. Vibration time: Period cycled for four hours in each of 3 mutual perpendicular directions. 3. Amplitude: 1.5 mm max.
5	Mechanical Shock	Inductance change: Within $\pm 10\%$ Without mechanical damage such as break	1. Peak value: 100 G, Duration of pulse: 6ms 2. 3 times in each positive and negative direction of 3 mutual perpendicular directions;
6	Substrate Bending	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	1.Bending speed is 0.5mm/sec, 2.While the bending width reaches 2mm, keep it for 60 sec
Endurance Reliability			
No.	Item	Specification and Requirement	Test Method
7	Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	Repeat 1000 cycles as follow: (-55 ± 2 °C; 30 $\pm$ 3 min) $\rightarrow$ ($+125^{\circ}\text{C} \pm 2$ °C , 30 $\pm$ 3 min)
8	Low Temperature Storage	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	Store temperature: -55 ± 2 °C, 1000 + 4 / -0 hours;
9	High Temperature Storage	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	Store temperature: $+125^{\circ}\text{C} \pm 2$ °C, 1000 + 4 / -0 hours;
10	High Temperature & Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	$85^{\circ}\text{C} 85\% \text{RH}$,1000+4/-0 hours;

Tape Packaging Dimensions



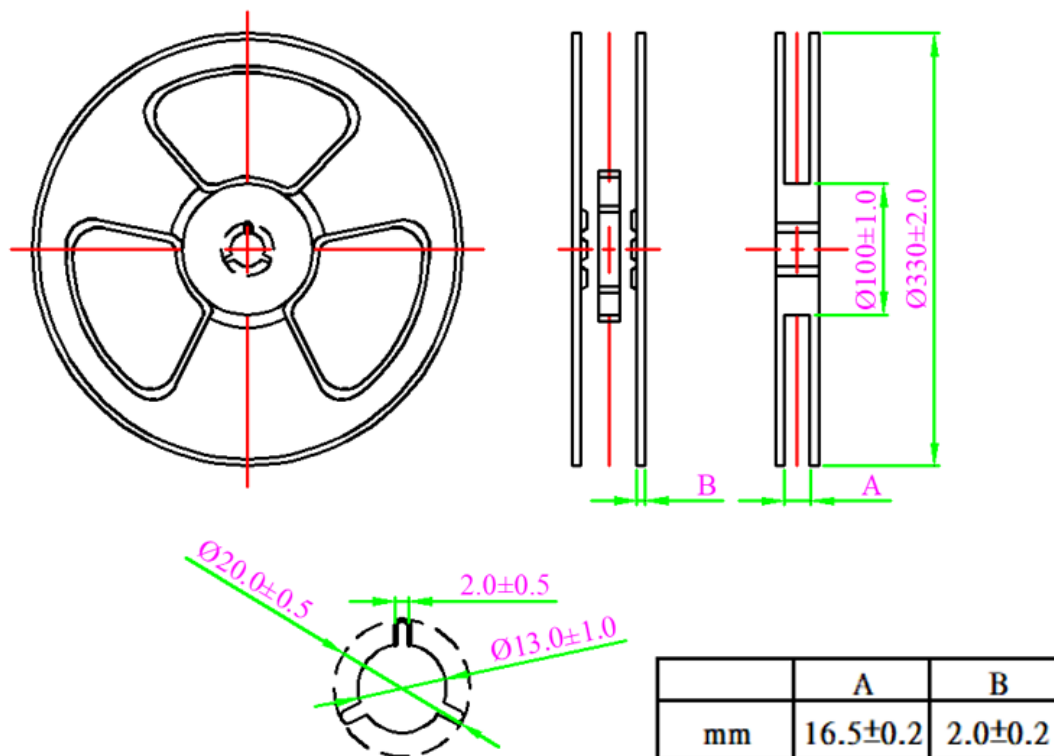
A0	B0	K0	t
4.8±0.10	4.8±0.10	3.6±0.15	0.35±0.05

Taping dimension and tape direction ,Leader ,Trailer, section dimension



Leader section	Min.400mm
Carrier tape start size	Min.100mm
Trailer section size	Min.160mm

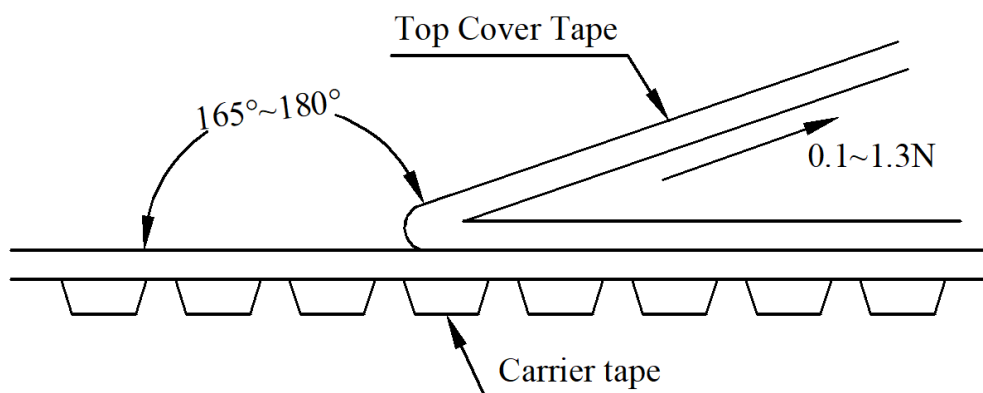
Reel Dimensions



• Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N



• Numbers of taping

2000pieces/reel